



PRODUCT DATASHEET



- PTH/THT Lamp
- 3mm Round 5.3t
- ▶ Infrared IR (850nm)





FEATURES:

- Package: PTH/THT 3mm Round 5.3t LED Lamp
- Forward Current: 20mA
- Forward Voltage (typ.): 1.4V
- Radiant Intensity (typ.): 18mW/sr@20mA
- Colour: Infrared IR
- Peak Wavelength (typ.): 850nm
- Viewing Angle: 30°
 - Materials:
 - Die: GaAlAs
 - Resin: Epoxy (Water Clear)
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- Grouping Parameters:
 - Forward voltage
 - Luminous intensity
 - Peak wavelength
- Soldering Methods: Hand; Soldering Heat (DIP)
- MSL Level: acc. to JEDEC Level 3
- Packing: 500pcs/bulk

3mm Round Lamp

APPLICATIONS:

NOF00L32

- Remote Control
- Smoke Detector
- Photo Detector
- Burglar Alarm

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- Computer I/O Peripheral
- Automatic Control System
- Industrial Application



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Continuous Forward Current	lf	60	mA
Peak Forward Current Width 10us Duty 1%	IFP	1	А
Reverse Current @5V	IR	100	μΑ
Reverse Voltage	V _R	5	V
Power Dissipation	PD	100	mW
Operating Temperature	Topr	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

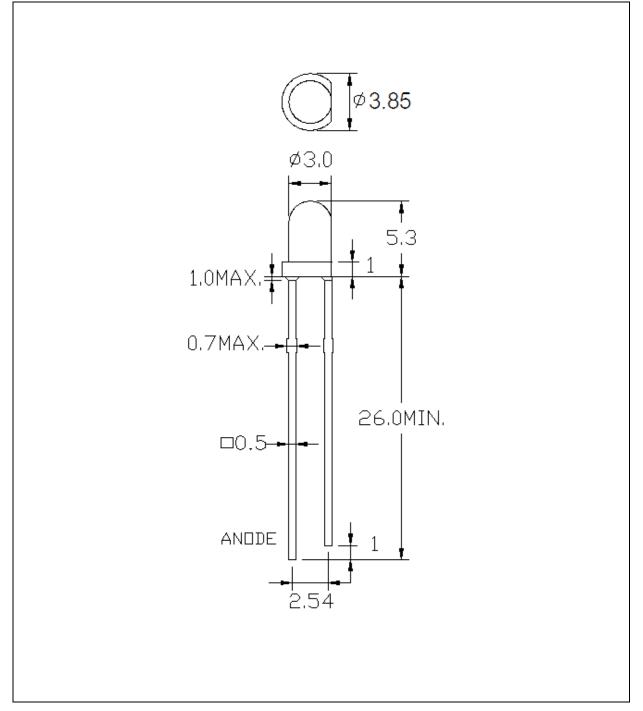
Parameter Symbol		Values			Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	VF		1.4	1.7	V	I⊧=20mA
Radiant Intensity	le	13	18		mW/sr	I⊧=20mA
Peak Wavelength	λ_{P}		850		nm	I⊧=20mA
Spectral Line Half Bandwidth	Δλ		42		nm	I⊧=20mA
Viewing Angle	2 θ 1/2		30		deg	I⊧=20mA
Rise Time	T _R			15	nS	
Fall Time	$T_{\rm F}$			10	nS	

1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle($2\theta_{1/2}$) ±5%



OUTLINE DIMENSION:

Package Dimension:



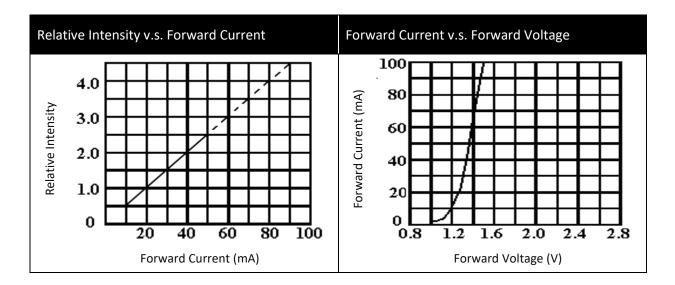
1. All dimensions are in millimetre (mm).

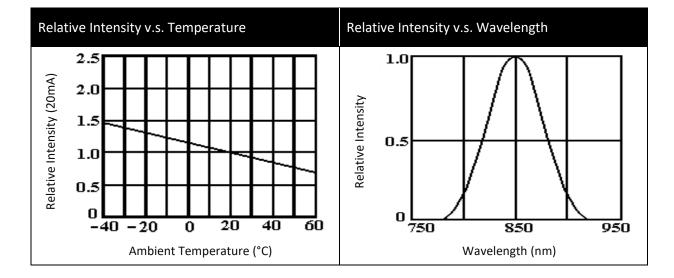
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2. Tolerance ±0.2mm, unless otherwise noted.



ELECTRO-OPTICAL CHARACTERISTICS:





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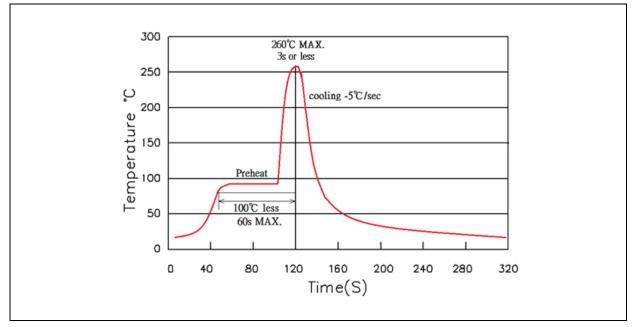


RECOMMENDED SOLDERING PROFILE:

Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

Soldering Heat (DIP):



Note:

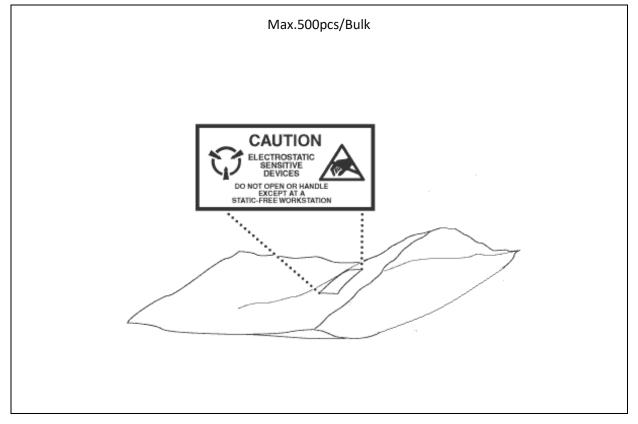
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- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:



Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	16/04/2023	Datasheet set-up.